- Qualification in Accordance With AEC-Q100<sup>†</sup>
- Qualified for Automotive Applications
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- 1 A Low-Dropout Voltage Regulator
- Available in 1.5-V, 1.8-V, 2.5-V, 2.7-V, 2.8-V, 3.0-V, 3.3-V, 5.0-V Fixed Output and Adjustable Versions
- Dropout Voltage Down to 230 mV at 1 A (TPS76750)
- Ultralow 85 μA Typical Quiescent Current
- Fast Transient Response

- 2% Tolerance Over Specified Conditions for Fixed-Output Versions
- Open Drain Power-On Reset With 200-ms Delay (See TPS768xx for PG Option)
- 20-Pin TSSOP PowerPAD<sup>TM</sup> (PWP) Package
- Thermal Shutdown Protection

PWP PACKAGE (TOP VIEW)							
GND/HSINK [ GND/HSINK [ GND [ EN [ IN [ IN [ GND/HSINK ] GND/HSINK [	1 2 3 4 5 6 7 8 9 10	20 19 18 17 16 15 14 13 12 11	GND/HSINK GND/HSINK NC NC RESET FB/NC OUT OUT GND/HSINK GND/HSINK				

NC – No internal connection

#### description

This device is designed to have a fast transient response and be stable with  $10-\mu$ F low ESR capacitors. This combination provides high performance at a reasonable cost.

Because the PMOS device behaves as a low-value resistor, the dropout voltage is very low (typically 230 mV at an output current of 1 A for the TPS76750) and is directly proportional to the output current. Additionally, since the PMOS pass element is a voltage-driven device, the quiescent current is very low and independent of output loading (typically 85  $\mu$ A over the full range of output current, 0 mA to 1 A). These two key specifications yield a significant improvement in operating life for battery-powered systems. This LDO family also features a sleep mode; applying a TTL high signal to EN (enable) shuts down the regulator, reducing the quiescent current to 1  $\mu$ A at T<sub>J</sub> = 25°C.

The RESET output of the TPS767xx initiates a reset in microcomputer and microprocessor systems in the event of an undervoltage condition. An internal comparator in the TPS767xx monitors the output voltage of the regulator to detect an undervoltage condition on the regulated output voltage.

The TPS767xx is offered in 1.5-V, 1.8-V, 2.5-V, 2.7-V, 2.8-V, 3.0-V, 3.3-V, and 5.0-V fixed-voltage versions and in an adjustable version (programmable over the range of 1.5 V to 5.5 V). Output voltage tolerance is specified as a maximum of 2% over line, load, and temperature ranges. The TPS767xx family is available in a 20-pin PWP package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

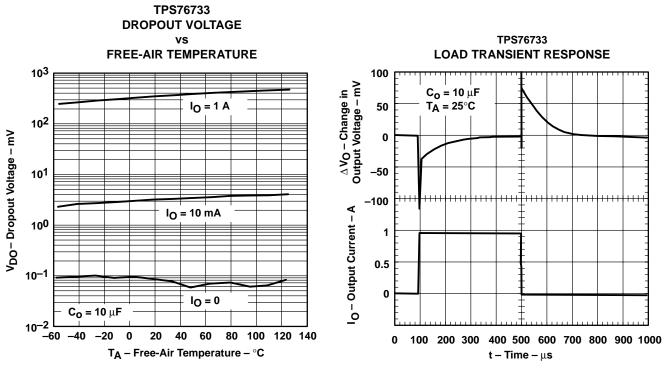
PowerPAD is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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<sup>&</sup>lt;sup>†</sup> Contact factory for details. Q100 qualification data available on request.



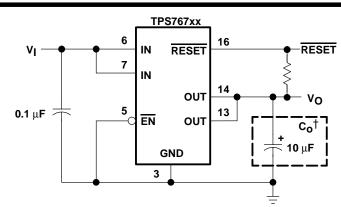
#### AVAILABLE OPTIONS

AVAILABLE OF HONS					
Tj	OUTPUT VOLTAGE (V)	TSSOP (PWP) <sup>†</sup>			
	TYP				
	5.0	TPS76750QPWPRQ1			
	3.3	TPS76733QPWPRQ1			
	3.0	TPS76730QPWPRQ1 <sup>‡</sup>			
	2.8	TPS76728QPWPRQ1 <sup>‡</sup>			
-40°C to 125°C	2.7	TPS76727QPWPRQ1 <sup>‡</sup>			
40 0 10 123 0	2.5	TPS76725QPWPRQ1			
	1.8	TPS76718QPWPRQ1			
	1.5	TPS76715QPWPRQ1			
	Adjustable 1.5 V to 5.5 V	TPS76701QPWPRQ1			

<sup>†</sup> Available taped and reeled in quantities of 2000 per reel.

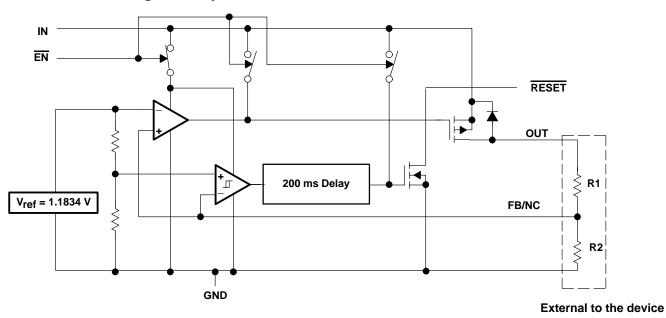
<sup>‡</sup> This devices is product preview.





<sup>†</sup> See application information section for capacitor selection details.

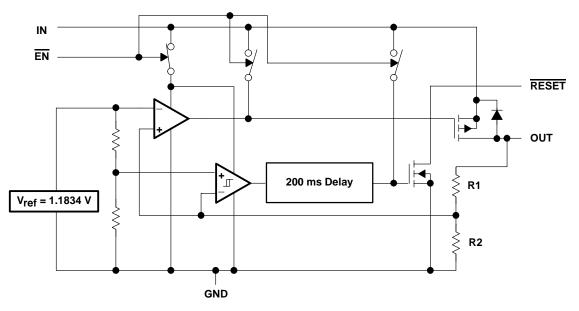
#### Figure 1. Typical Application Configuration (For Fixed Output Options)



functional block diagram—adjustable version



### functional block diagram—fixed-voltage version



#### **Terminal Functions**

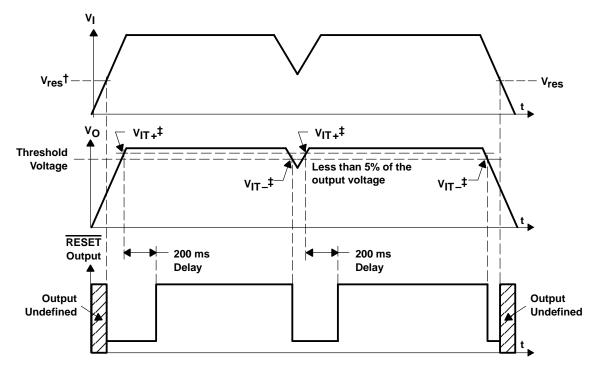
#### **PWP** Package

TERMINAL		1/0				
NAME	NO.	I/O	DESCRIPTION			
EN	5	Ι	Enable input			
FB/NC	15	Ι	Feedback input voltage for adjustable device (no connect for fixed options)			
GND	3		Regulator ground			
GND/HSINK	1, 2, 9, 10, 11, 12, 19, 20		Ground/heatsink			
IN	6, 7	Ι	Input voltage			
NC	4, 8, 17, 18		No connect			
OUT	13, 14	0	Regulated output voltage			
RESET	16	0	RESET output			



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#### timing diagram



<sup>†</sup> V<sub>res</sub> is the minimum input voltage for a valid RESET. The symbol V<sub>res</sub> is not currently listed within EIA or JEDEC standards for semiconductor symbology.

 $V_{IT}$  –Trip voltage is typically 5% lower than the output voltage (95%V<sub>O</sub>) V<sub>IT</sub> to V<sub>IT</sub> is the hysteresis voltage.



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Input voltage range <sup>‡</sup> , V <sub>I</sub>	
Maximum RESET voltage	16.5 V
Peak output current	Internally limited
Output voltage, V <sub>O</sub> (OUT, FB)	
Continuous total power dissipation	See dissipation rating tables
Operating virtual junction temperature range, T <sub>J</sub>	–40°C to 125°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C
ESD rating, HBM	

<sup>+</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>‡</sup> All voltage values are with respect to network terminal ground.

#### **DISSIPATION RATING TABLE – FREE-AIR TEMPERATURES**

PACKAGE	AIR FLOW (CFM)	T <sub>A</sub> < 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING
DWD	0	2.9 W	23.5 mW/°C	1.9 W	1.5 W
PWP§	300	4.3 W	34.6 mW/°C	2.8 W	2.2 W
	0	3 W	23.8 mW/°C	1.9 W	1.5 W
PWP¶	300	7.2 W	57.9 mW/°C	4.6 W	3.8 W

§ This parameter is measured with the recommended copper heat sink pattern on a 1-layer PCB, 5-in × 5-in PCB, 1 oz. copper, 2-in × 2-in coverage (4 in<sup>2</sup>).

This parameter is measured with the recommended copper heat sink pattern on a 8-layer PCB, 1.5-in × 2-in PCB, 1 oz. copper with layers 1, 2, 4, 5, 7, and 8 at 5% coverage (0.9 in<sup>2</sup>) and layers 3 and 6 at 100% coverage (6 in<sup>2</sup>). For more information, refer to TI technical brief SLMA002.

#### recommended operating conditions

	MIN	MAX	UNIT
Input voltage, VI#	2.7	10	V
Output voltage range, VO	1.5	5.5	V
Output current, IO (see Note 1)	0	1.0	А
Operating virtual junction temperature, TJ (see Note 1)	-40	125	°C

To calculate the minimum input voltage for your maximum output current, use the following equation: V<sub>I</sub>(min) = V<sub>O</sub>(max) + V<sub>DO</sub>(max load).
NOTE 1: Continuous current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.



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# electrical characteristics ove<u>r re</u>commended operating free-air temperature range, $V_I = V_{O(tvp)} + 1 V$ , $I_O = 1 mA$ , $\overline{EN} = 0 V$ , $C_o = 10 \mu F$ (unless otherwise noted)

PARAMETER		TEST CO	NDITIONS	MIN	TYP	MAX	UNIT
		$1.5 \text{ V} \le \text{V}_{O} \le 5.5 \text{ V},$	TJ = 25°C		VO		
	TPS76701	$1.5 \text{ V} \le \text{V}_{O} \le 5.5 \text{ V},$	$T_{J} = -40^{\circ}C$ to $125^{\circ}C$	0.98VO		1.02VO	
		T <sub>J</sub> = 25°C,	2.7 V < V <sub>IN</sub> < 10 V		1.5		
	TPS76715	$T_{J} = -40^{\circ}C$ to 125°C,	2.7 V < V <sub>IN</sub> < 10 V	1.470		1.530	
		T <sub>J</sub> = 25°C,	2.8 V < V <sub>IN</sub> < 10 V		1.8		
	TPS76718	$T_{J} = -40^{\circ}C$ to 125°C,	2.8 V < V <sub>IN</sub> < 10 V	1.764		1.836	
		TJ = 25°C,	3.5 V < V <sub>IN</sub> < 10 V		2.5		
	TPS76725	$T_{J} = -40^{\circ}C$ to 125°C,	3.5 V < V <sub>IN</sub> < 10 V	2.450		2.550	
Output voltage (10 µA to 1 A load)		TJ = 25°C,	3.7 V < V <sub>IN</sub> < 10 V		2.7		
(see Note 2)	TPS76727	$T_{J} = -40^{\circ}C$ to 125°C,	3.7 V < V <sub>IN</sub> < 10 V	2.646		2.754	V
	TD070700	T <sub>J</sub> = 25°C,	3.8 V < V <sub>IN</sub> < 10 V		2.8		
	TPS76728	$T_{J} = -40^{\circ}C$ to $125^{\circ}C$ ,	3.8 V < V <sub>IN</sub> < 10 V	2.744		2.856	
	TD070700	T <sub>J</sub> = 25°C,	4.0 V < V <sub>IN</sub> < 10 V		3.0		
	TPS76730	$T_J = -40^{\circ}C$ to $125^{\circ}C$ ,	4.0 V < V <sub>IN</sub> < 10 V	2.940		3.060	
	TPS76733	$T_J = 25^{\circ}C$ ,	4.3 V < V <sub>IN</sub> < 10 V		3.3		
		$T_J = -40^{\circ}C$ to $125^{\circ}C$ ,	4.3 V < V <sub>IN</sub> < 10 V	3.234		3.366	
	TPS76750	T <sub>J</sub> = 25°C,	6.0 V < V <sub>IN</sub> < 10 V		5.0		
		$T_J = -40^{\circ}C$ to $125^{\circ}C$ ,		4.900		5.100	
Quiescent current (GND current)		10 μA < I <sub>O</sub> < 1 A,	T <sub>J</sub> = 25°C		85		
EN = 0V, (see Note 2)		I <sub>O</sub> = 1 A,	$T_J = -40^{\circ}C$ to $125^{\circ}C$			125	μA
Output voltage line regulation ( $\Delta V_{O}/V_{0}$ (see Notes 2 and 3)	<b>/</b> O )	$V_{O} + 1 V < V_{I} \le 10 V,$	T <sub>J</sub> = 25°C		0.01		%/V
Load regulation					3		mV
Output noise voltage (TPS76718)		BW = 200 Hz to 100 k $C_0 = 10 \mu\text{F},$	Hz, I <sub>C</sub> = 1 A, T <sub>J</sub> = 25°C		55		μVrms
Output current limit		VO = 0 V			1.7	2	А
Thermal shutdown junction temperate	ure				150		°C
Standby current		EN = VI,	TJ = 25°C, 2.7 V < VI < 10 V		1		μA
		EN = V <sub>I,</sub>	$T_J = -40^{\circ}C \text{ to } 125^{\circ}C$ 2.7 V < V <sub>I</sub> < 10 V			10	μA
FB input current	TPS76701	FB = 1.5 V		1	2		nA
High level enable input voltage				1.7			V
Low level enable input voltage						0.9	V
Power supply ripple rejection (see No	ote 2)	f = 1 KHz, TJ = 25°C	C <sub>O</sub> = 10 μF,		60		dB

NOTES: 2. Minimum IN operating voltage is 2.7 V or  $V_{O(typ)}$  + 1 V, whichever is greater. Maximum IN voltage 10V. 3. If  $V_{O} \le 1.8$  V then  $V_{Imax} = 10$  V,  $V_{Imin} = 2.7$  V:

Line Reg. (mV) = 
$$(\%/V) \times \frac{V_O(V_{Imax} - 2.7 V)}{100} \times 1000$$

If  $V_O \ge 2.5$  V then  $V_{Imax} = 10$  V,  $V_{Imin} = V_O + 1$  V:

Line Reg. (mV) = 
$$(\%/V) \times \frac{V_O(V_{Imax} - (V_O + 1V))}{100} \times 1000$$



#### electrical characteristics <u>over</u> recommended operating free-air temperature $V_I = V_{O(typ)} + 1 V$ , $I_O = 1 \text{ mA}$ , $\overline{EN} = 0 V$ , $C_o = 10 \mu F$ (unless otherwise noted) (continued) range,

	PARAMETER		TES	T CONDITIONS	MIN	TYP	MAX	UNIT
	Minimum input voltage for valid R	ESET	IO(RESET) = 30	00 μΑ		1.1		V
	Trip threshold voltage		VO decreasing		92		98	%VO
<b>D</b> 1	Hysteresis voltage		Measured at VC	)		0.5		%VO
Reset	Output low voltage		V <sub>I</sub> = 2.7 V,	IO(RESET) = 1 mA		0.15	0.4	V
	Leakage current		V(RESET) = 5 V	/			1	μA
	RESET time-out delay					200		ms
land a			EN = 0 V		-1	0	1	
input c	urrent (EN)		$\overline{EN} = V_{I}$		-1		1	μA
		TD070700	I <sub>O</sub> = 1 A,	T <sub>J</sub> = 25°C		500		
		TPS76728	I <sub>O</sub> = 1 A,	$T_{J} = -40^{\circ}C \text{ to } 125^{\circ}C$			825	
		<b>TD070700</b>	I <sub>O</sub> = 1 A,	$T_J = 25^{\circ}C$		450		
Dropou	it voltage (see Note 4)	TPS76730	I <sub>O</sub> = 1 A,	$T_J = -40^{\circ}C$ to $125^{\circ}C$			675	
TPS76733		I <sub>O</sub> = 1 A,	$T_J = 25^{\circ}C$		350		mV	
		I <sub>O</sub> = 1 A,	$T_J = -40^{\circ}C$ to $125^{\circ}C$			575		
			I <sub>O</sub> = 1 A,	$T_J = 25^{\circ}C$		230		
		TPS76750	I <sub>O</sub> = 1 A,	T <sub>J</sub> = −40°C to 125°C			380	

NOTE 4: IN voltage equals V<sub>O</sub>(typ) - 100 mV; TPS76701 output voltage set to 3.3 V nominal with external resistor divider. TPS76715, TPS76718, TPS76725, and TPS76727 dropout voltage limited by input voltage range limitations (i.e., TPS76730 input voltage needs to drop to 2.9 V for purpose of this test).

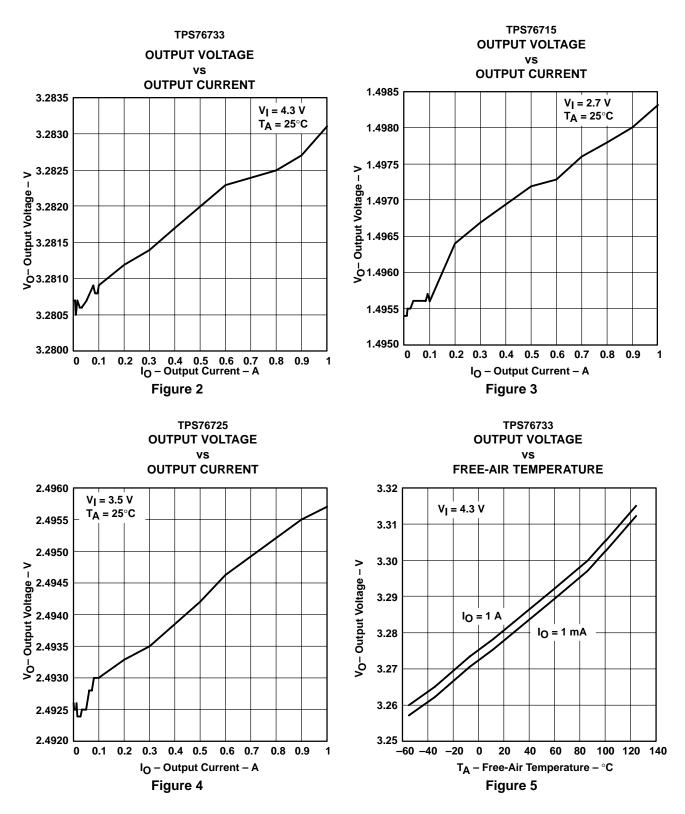
#### **TYPICAL CHARACTERISTICS**

#### **Table of Graphs**

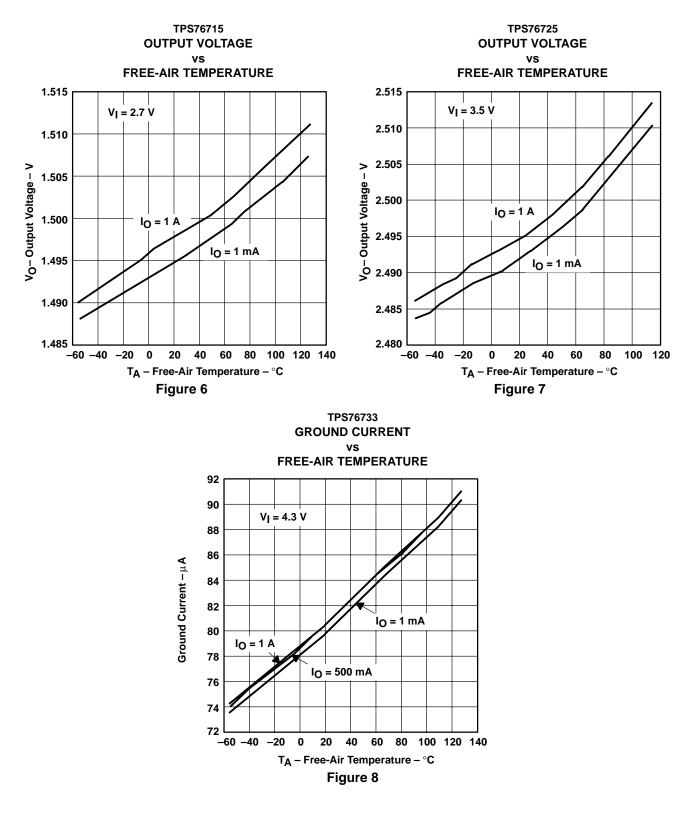
			FIGURE
.,		vs Output current	2, 3, 4
Vo	Output voltage	vs Free-air temperature	5, 6, 7
	Ground current	vs Free-air temperature	8, 9
	Power supply ripple rejection	vs Frequency	10
	Output spectral noise density	vs Frequency	11
	Input voltage (min)	vs Output voltage	12
Zo	Output impedance	vs Frequency	13
VDO	Dropout voltage	vs Free-air temperature	14
	Line transient response		15, 17
	Load transient response		16, 18
VO	Output voltage	vs Time	19
	Dropout voltage	vs Input voltage	20
	Equivalent series resistance (ESR)	vs Output current	22 – 25



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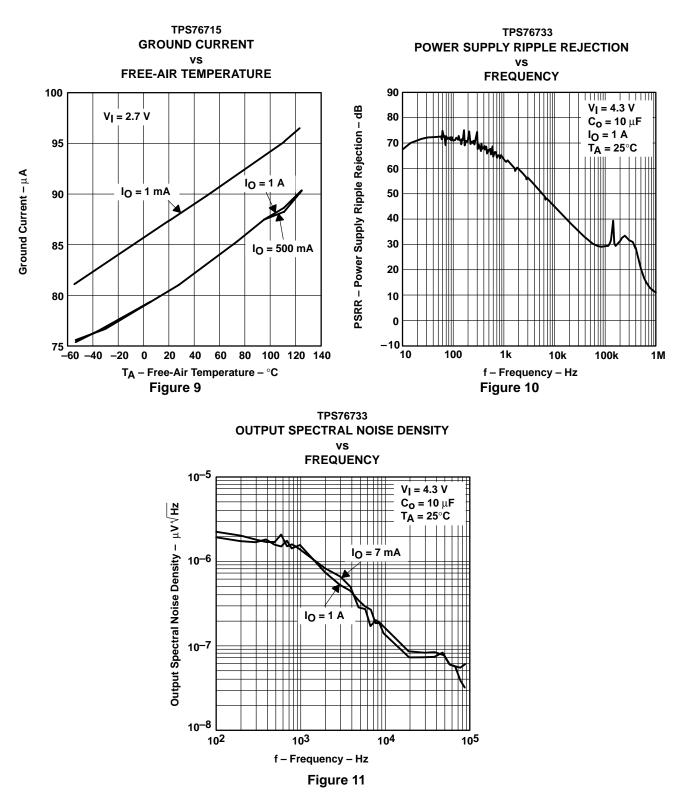






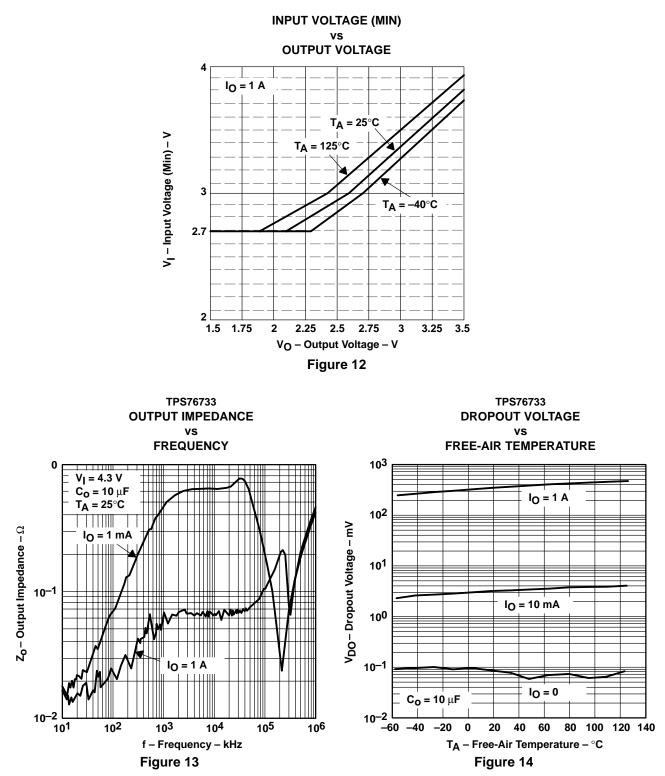


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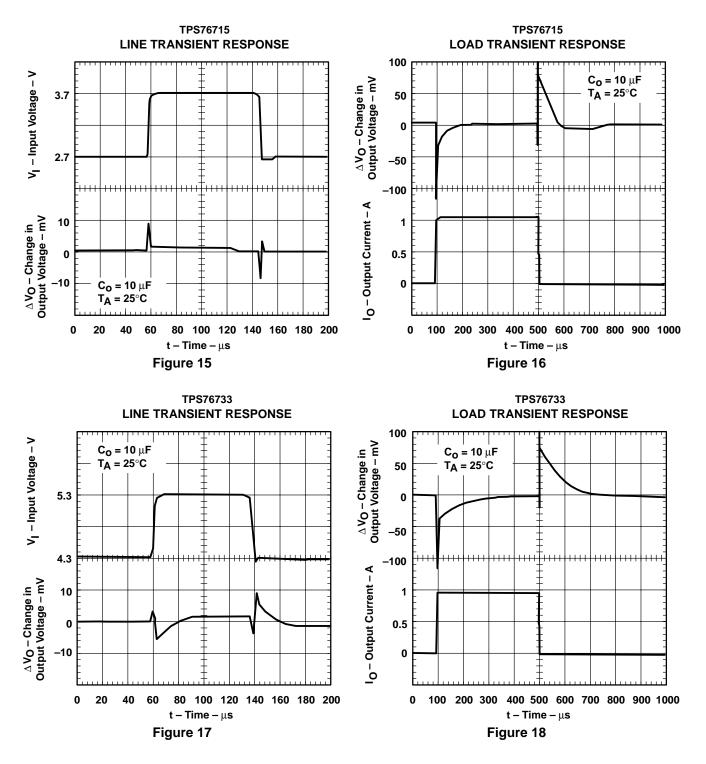














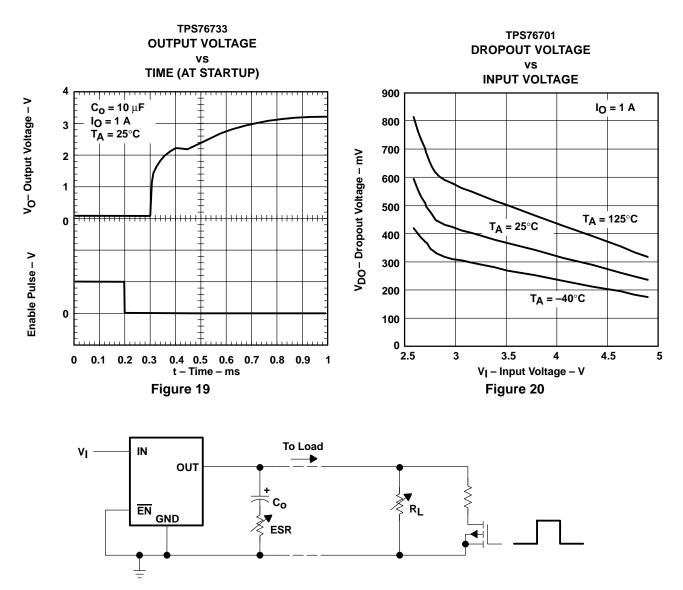
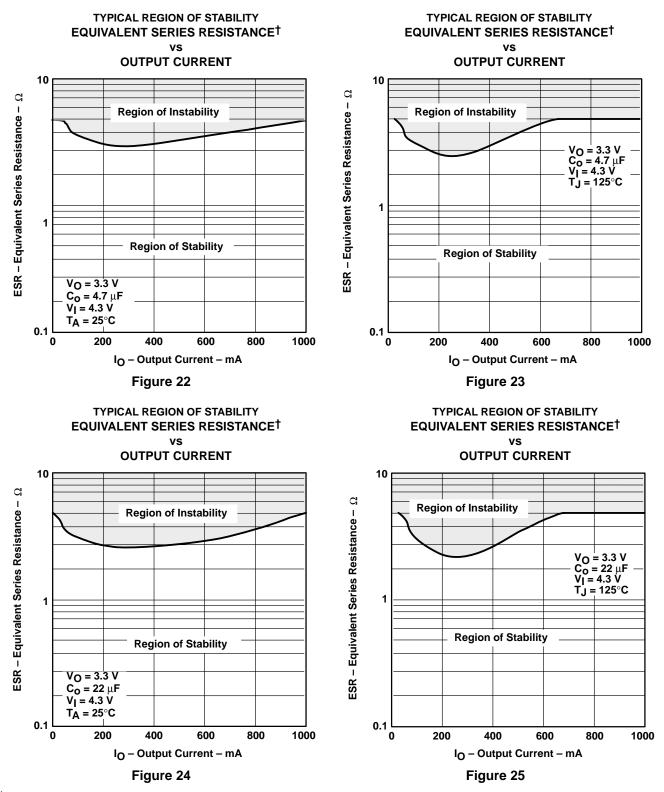


Figure 21. Test Circuit for Typical Regions of Stability (Figures 22 through 25) (Fixed Output Options)



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#### **TYPICAL CHARACTERISTICS**

† Equivalent series resistance (ESR) refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to Co.



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#### **APPLICATION INFORMATION**

The TPS767xx family includes eight fixed-output voltage regulators (1.5 V, 1.8 V, 2.5 V, 2.7 V, 2.8 V, 3.0 V, 3.3 V, and 5.0 V), and an adjustable regulator, the TPS76701 (adjustable from 1.5 V to 5.5 V).

#### device operation

The TPS767xx features very low quiescent current, which remains virtually constant even with varying loads. Conventional LDO regulators use a pnp pass element, the base current of which is directly proportional to the load current through the regulator ( $I_B = I_C/\beta$ ). The TPS767xx uses a PMOS transistor to pass current; because the gate of the PMOS is voltage driven, operating current is low and invariable over the full load range.

Another pitfall associated with the pnp-pass element is its tendency to saturate when the device goes into dropout. The resulting drop in  $\beta$  forces an increase in I<sub>B</sub> to maintain the load. During power up, this translates to large start-up currents. Systems with limited supply current may fail to start up. In battery-powered systems, it means rapid battery discharge when the voltage decays below the minimum required for regulation. The TPS767xx quiescent current remains low even when the regulator drops out, eliminating both problems.

The TPS767xx family also features a shutdown mode that places the output in the high-impedance state (essentially equal to the feedback-divider resistance) and reduces quiescent current to 2  $\mu$ A. If the shutdown feature is not used, EN should be tied to ground.

#### minimum load requirements

The TPS767xx family is stable even at zero load; no minimum load is required for operation.

#### FB—pin connection (adjustable version only)

The FB pin is an input pin to sense the output voltage and close the loop for the adjustable option. The output voltage is sensed through a resistor divider network to close the loop as shown in Figure 27. Normally, this connection should be as short as possible; however, the connection can be made near a critical circuit to improve performance at that point. Internally, FB connects to a high-impedance wide-bandwidth amplifier and noise pickup feeds through to the regulator output. Routing the FB connection to minimize/avoid noise pickup is essential.

#### external capacitor requirements

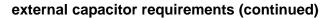
An input capacitor is not usually required; however, a ceramic bypass capacitor (0.047  $\mu$ F or larger) improves load transient response and noise rejection if the TPS767xx is located more than a few inches from the power supply. A higher-capacitance electrolytic capacitor may be necessary if large (hundreds of milliamps) load transients with fast rise times are anticipated.

Like all low dropout regulators, the TPS767xx requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance value is 10  $\mu$ F and the ESR (equivalent series resistance) must be between 50 m $\Omega$  and 1.5  $\Omega$ . Capacitor values 10  $\mu$ F or larger are acceptable, provided the ESR is less than 1.5  $\Omega$ . Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described above. Most of the commercially available 10  $\mu$ F surface-mount ceramic capacitors, including devices from Sprague and Kemet, meet the ESR requirements stated above.



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#### **APPLICATION INFORMATION**



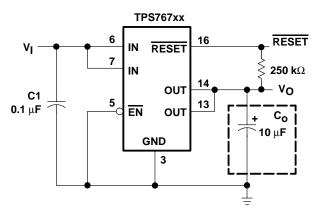


Figure 26. Typical Application Circuit (Fixed Versions)

#### programming the TPS76701 adjustable LDO regulator

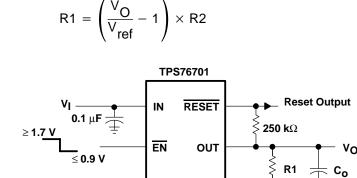
The output voltage of the TPS76701 adjustable regulator is programmed using an external resistor divider as shown in Figure 27. The output voltage is calculated using:

$$V_{O} = V_{ref} \times \left(1 + \frac{R_1}{R_2}\right)$$
(1)

Where:

V<sub>ref</sub> = 1.1834 V typ (the internal reference voltage)

Resistors R1 and R2 should be chosen for approximately 50-µA divider current. Lower value resistors can be used but offer no inherent advantage and waste more power. Higher values should be avoided as leakage currents at FB increase the output voltage error. The recommended design procedure is to choose R2 = 30.1 k $\Omega$  to set the divider current at 50  $\mu$ A and then calculate R1 using:



FB/NC GND

OUTPUT VOLTAGE
PROGRAMMING GUIDE

OUTPUT VOLTAGE	R1	R2	UNIT
2.5 V	33.2	30.1	kΩ
3.3 V	53.6	30.1	kΩ
3.6 V	61.9	30.1	kΩ
4.75 V	90.8	30.1	kΩ

Figure 27. TPS76701 Adjustable LDO Regulator Programming

R2



(2)

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#### APPLICATION INFORMATION

#### reset indicator

The TPS767xx features a RESET output that can be used to monitor the status of the regulator. The internal comparator monitors the output voltage: when the output drops to between 92% and 98% of its nominal regulated value, the RESET output transistor turns on, taking the signal low. The open-drain output requires a pullup resistor. If not used, it can be left floating. RESET can be used to drive power-on reset circuitry or as a low-battery indicator. RESET does not assert itself when the regulated output voltage falls outside the specified 2% tolerance, but instead reports an output voltage low relative to its nominal regulated value (refer to timing diagram for start-up sequence).

#### regulator protection

The TPS767xx PMOS-pass transistor has a built-in back diode that conducts reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.

The TPS767xx also features internal current limiting and thermal protection. During normal operation, the TPS767xx limits output current to approximately 1.7 A. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 150°C(typ), thermal-protection circuitry shuts it down. Once the device has cooled below 130°C(typ), regulator operation resumes.

#### power dissipation and junction temperature

Specified regulator operation is assured to a junction temperature of 125°C; the maximum junction temperature should be restricted to 125°C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation, PD(max), and the actual dissipation, PD, which must be less than or equal to P<sub>D(max)</sub>.

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_J max - T_A}{R_{\theta JA}}$$

Where:

T<sub>1</sub>max is the maximum allowable junction temperature.

 $R_{\theta JA}$  is the thermal resistance junction-to-ambient for the package, i.e., 172°C/W for the 8-terminal SOIC and 32.6°C/W for the 20-terminal PWP with no airflow.

T<sub>A</sub> is the ambient temperature.

The regulator dissipation is calculated using:

$$\mathsf{P}_{\mathsf{D}} = \left(\mathsf{V}_{\mathsf{I}} - \mathsf{V}_{\mathsf{O}}\right) \times \mathsf{I}_{\mathsf{O}}$$

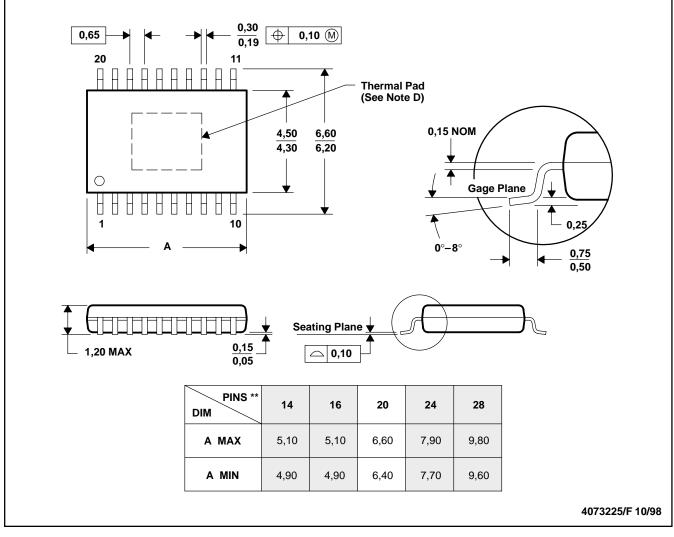
Power dissipation resulting from quiescent current is negligible. Excessive power dissipation will trigger the thermal protection circuit.



PowerPAD<sup>™</sup> PLASTIC SMALL-OUTLINE

MECHANICAL DATA

PWP (R-PDSO-G\*\*) 20 PINS SHOWN



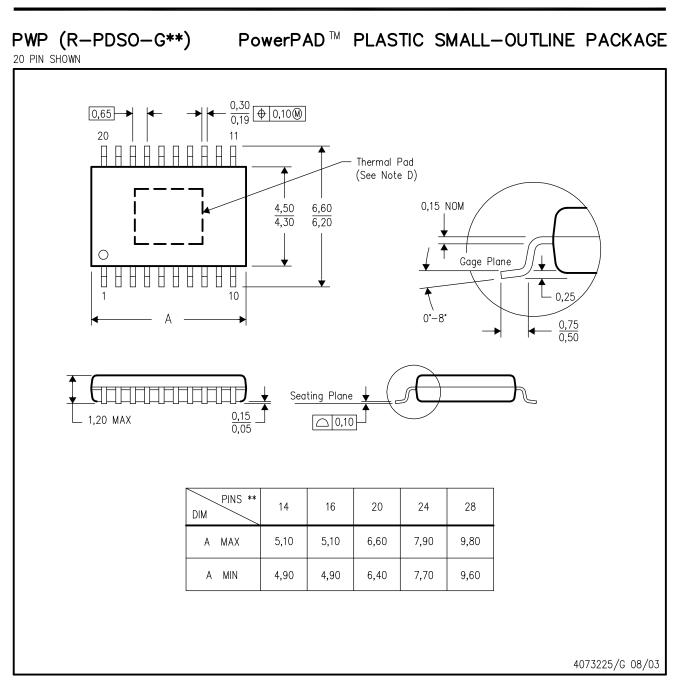
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusions.

D. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.

E. Falls within JEDEC MO-153

PowerPAD is a trademark of Texas Instruments Incorporated.



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusions.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <a href="http://www.ti.com">http://www.ti.com</a>.
- E. Falls within JEDEC MO-153

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